

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	19295	(semiconductor or die or chip or IC) and (adhesive or glue) same (reference or align\$4)	USPAT	2004/03/29 19:36
2	BRS	3766	(semiconductor or die or chip or IC) and (adhesive or glue) near (lines or layer or film) same (reference or align\$4)	USPAT	2004/03/23 12:48
3	BRS	1316	(semiconductor or die or chip or IC) and (adhesive or glue) near (lines or layer or film) with (reference or align\$4)	USPAT	2004/03/25 13:02
4	BRS	2143	257/676	USPAT	2004/03/25 13:02
5	BRS	1316	(semiconductor or die or chip or IC) and (adhesive or glue) near (lines or layer or film) with (reference or align\$4)	USPAT	2004/03/25 13:02
6	BRS	2098	257/676 not ((semiconductor or die or chip or IC) and (adhesive or glue) near (lines or layer or film) with (reference or align\$4))	USPAT	2004/03/25 13:02
7	BRS	1835	257/676 and (encapsula\$4 or mold\$3 or cover\$3 near resin or resin)	USPAT	2004/03/25 17:31

	Type	Hits	Search Text	DBs	Time Stamp
8	BRS	1835	257/676 and (encapsula\$4 or mold\$3 or cover\$3 near resin or resin)	USPAT	2004/03/ 25 17:31
9	BRS	3062	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 25 17:32
10	BRS	1227	257/676 not (257/676 and (encapsula\$4 or mold\$3 or cover\$3 near resin or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 25 17:32
11	BRS	1294	257/777 and (adhesive or glue or under near fill\$3 or "underfill")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 10:13
12	BRS	454	257/777 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:21
13	BRS	47	"5027253"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 10:36
14	BRS	4	5027253.pn. or 11219978.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 10:39
15	BRS	7	5027253.pn. or 11219978.pn. or 2000068644.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 10:39
16	BRS	9	5027253.pn. or 11219978.pn. or 2000068644.pn. or 04283987.pn. or 04225594.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 10:42

	Type	Hits	Search Text	DBs	Time Stamp
17	BRS	495	257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:27
18	BRS	99	257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:28
19	BRS	31746	(semiconductor or die or chip or IC) and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:29
20	BRS	12267	(semiconductor or die or chip or IC) and (adhesive or glue or under near fill\$3 or "underfill") with (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:30
21	BRS	12008	(semiconductor or die or chip or IC) and (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:30
22	BRS	3626	(semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:31

	Type	Hits	Search Text	DBs	Time Stamp
23	BRS	1407	((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) and "257"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:33
24	BRS	3455	((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:34

	Type	Hits	Search Text	DBs	Time Stamp
25	BRS	1154	(((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:34
26	BRS	2024	((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3))))	USPAT	2004/03/ 29 12:35

	Type	Hits	Search Text	DBs	Time Stamp
27	BRS	792	(((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))) and (((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or	USPAT	2004/03/29 12:49

	Type	Hits	Search Text	DBs	Time Stamp
28	BRS	1232	(((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))) not (((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or	USPAT	2004/03/29 12:58

	Type	Hits	Search Text	DBs	Time Stamp
29	BRS	0	(((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))) not (((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or	USPAT	2004/03/ 29 12:58

	Type	Hits	Search Text	DBs	Time Stamp
30	BRS	1431	(((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or mark\$3 or cod\$3 or referenc\$3)) not ((257/787 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)) or (257/797 and (adhesive or glue or under near fill\$3 or "underfill") same (align\$4 or mark\$3 or cod\$3 or referenc\$3)))) not (((semiconductor or die or chip or IC) same (adhesive or glue) with (align\$4 or	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 12:59
31	BRS	179	257/782 and (adhesive or glue) same (reference or align\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 19:43
32	BRS	389	257/783 and (adhesive or glue) same (reference or align\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/ 29 19:43